



# EVG<sup>®</sup>150

## Automated Resist Processing System



### Introduction

The EVG<sup>®</sup>150 is a fully- automated resist processing system providing high-throughput performance and supporting wafers up to 300 mm in diameter.

Designed as a fully modular platform, the EVG150 allows automated spray/spin/develop processes and high-throughput performance. The EVG150 guarantees highly uniform coats and improved repeatability. Wafers with high topography can be uniformly coated by EVG's OmniSpray technology, where traditional spin coating encounters limitations.

Technical Data	
Wafer diameter (substrate size)	up to 300 mm
Available modules	- Spin coat / OmniSpray <sup>®</sup> / develop - Bake / chill
Wafer handling options	- Single/double EE / edge handling / wafer flipping - Bowed / warped / thin wafer handling
Dispense options	- various resist dispense pumps to cover a wide range of viscosities up to 52000 cP - constant pressure dispense systems - EBR / BSR / pre-wet / bowl wash / liquid priming

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### Features

- Wafer sizes up to 300 mm
- Up to six process modules
- Customizable number - up to twenty bake/chill/vapor prime stacks
- Up to four FOUP load ports or cassette loading
- OmniSpray<sup>®</sup> ultrasonic atomization technology for conformal coating of extreme topographies
- Optional NanoSpray<sup>™</sup> module achieves conformal coating of 300-micron deep patterns with aspect ratios up to 1:10 and vertical sidewalls
- Extensive range of supported materials
- Megasonic technology for cleaning, sono-chemical processing and developing improves process efficiency and lowers the process time from hours to minutes
- Sophisticated and field-proven robot handling with dual end-effector capability ensures continuous high throughput
- Smart process control and data analysis features
  - equipment and process performance tracking and data analysis features
  - parallel / queueing task processing feature
  - smart handling features
  - occurrence and alarm analysis features
  - smart maintenance and tracking features

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